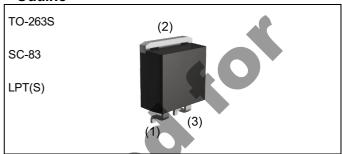
Nch 600V 7A Power MOSFET

V _{DSS}	600V
R _{DS(on)} (Max.)	0.730Ω
I _D	±7A
P _D	94W

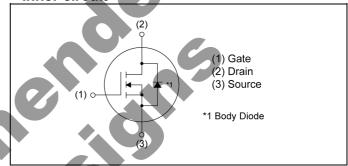
Outline



Features

- 1) Fast reverse recovery time (trr).
- 2) Low on-resistance.
- 3) Fast switching speed.
- 4) Gate-source voltage (V_{GSS}) guaranteed to be $\pm 30V$.
- 5) Drive circuits can be simple.
- 6) Pb-free plating; RoHS compliant

•Inner circuit



Packaging specifications

VI achae	Jing specifications	
	Packing	Embossed Tape
	Reel size (mm)	330
Type	Tape width (mm)	24
,	Basic ordering unit (pcs)	1000
	Taping code	TL
	Marking	R6007MNJ

Application

Switching Power Supply

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	600	V
Continuous drain current (T _c = 25°C)	I _D *1	±7	А
Pulsed drain current	I _{DP} *2	±21	Α
Gate - Source voltage	V_{GSS}	±30	V
Avalanche current, single pulse	I _{AS} *3	1.0	А
Avalanche energy, single pulse	E _{AS} *3	0.27	mJ
Power dissipation (T _c = 25°C)	P _D *4	94	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Daramatar	Cymah al	Values			l lait
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	-	1.32	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	4	265	°C

●Electrical characteristics (T_a = 25°C)

Symbol	Conditions	Values			Linit
Symbol	Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	600	-	1	V
	$V_{DS} = 600V, V_{GS} = 0V$				
I _{DSS}	$T_j = 25^{\circ}C$	-	-	100	μΑ
	T _j = 125°C	-	-	-	
I _{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA
V _{GS(th)}	$V_{DS} = 10V, I_D = 135\mu A$	3.0	-	5.0	V
	$V_{GS} = 10V, I_D = 3.5A$				
R _{DS(on)} *5	T _j = 25°C	-	0.540	0.730	Ω
	T _j = 125°C	-	-	-	
R_{G}	f = 1MHz, open drain	-	3.5	-	Ω
	I _{DSS} V _{GS(th)} R _{DS(on)} *5	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$ $V_{DS} = 600V, V_{GS} = 0V$ $T_j = 25^{\circ}C$ $T_j = 125^{\circ}C$ $V_{GS} = \pm 30V, V_{DS} = 0V$ $V_{GS(th)}$ $V_{DS} = 10V, I_D = 135\mu A$ $V_{GS} = 10V, I_D = 3.5A$ $V_{DS} = 125^{\circ}C$ $V_{DS} = 125^{\circ}C$ $V_{DS} = 125^{\circ}C$	$V_{(BR)DSS} V_{GS} = 0V, I_D = 1 \text{mA} \qquad 600$ $V_{DS} = 600V, V_{GS} = 0V$ $T_j = 25^{\circ}C \qquad -$ $T_j = 125^{\circ}C \qquad -$ $V_{GS} = \pm 30V, V_{DS} = 0V \qquad -$ $V_{GS(th)} V_{DS} = 10V, I_D = 135 \mu\text{A} \qquad 3.0$ $V_{GS} = 10V, I_D = 3.5 \text{A}$ $R_{DS(on)}^{*5} T_j = 25^{\circ}C \qquad -$ $T_j = 125^{\circ}C \qquad -$	$ \begin{array}{ c c c c c c } \hline Symbol & Conditions & \hline & Min. & Typ. \\ \hline & V_{(BR)DSS} & V_{GS} = 0V, I_D = 1 mA & 600 & - \\ \hline & V_{DS} = 600V, V_{GS} = 0V & & \\ \hline & I_{DSS} & T_j = 25^{\circ}C & - & - \\ \hline & T_j = 125^{\circ}C & - & - \\ \hline & V_{GS} = \pm 30V, V_{DS} = 0V & - & - \\ \hline & V_{GS(th)} & V_{DS} = 10V, I_D = 135 \mu A & 3.0 & - \\ \hline & V_{GS} = 10V, I_D = 3.5A & & \\ \hline & V_{DS} = 125^{\circ}C & - & 0.540 \\ \hline & T_j = 125^{\circ}C & - & - \\ \hline \end{array} $	$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$



● Electrical characteristics (T_a = 25°C)

Davamatar	Cymah al	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Forward Transfer Admittance	Y _{fs} *5	V _{DS} = 10V, I _D = 3.5A	2.0	-	-	S	
Input capacitance	C _{iss}	V _{GS} = 0V	-	465			
Output capacitance	C _{oss}	V _{DS} = 25V	-	545		pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	15	-		
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 300V$, $V_{GS} = 10V$	-(15	-		
Rise time	t _r *5	I _D = 3.5A	75	15	-	20	
Turn - off delay time	t _{d(off)} *5	R _L ~ 86.6Ω	-	30	-	ns	
Fall time	t _f *5	$R_G = 10\Omega$	-	15	-		

● Gate charge characteristics (T_a = 25°C)

Darameter	Symbol Conditions		Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	V _{DD} ≈ 300V	-	10	1	
Gate - Source charge	Q _{gs} *5	I _D = 7A	-	3.5	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	3.5	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 300V$, $I_D = 7A$	-	6.4	-	V

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \simeq 500 μ H, V_{DD} = 50V, R_G = 25 Ω , starting T_j = 25 $^{\circ}$ C

^{*4} Tc=25°C

^{*5} Pulsed

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Darameter	Cumb ol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	I _S *1	T _C = 25°C	-	-	7	А
Pulse forward current	I _{SP} *2		-	-	21	A
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 7A$	-	` \	1.5	V
Reverse recovery time	t _{rr} *5		-	60	-	ns
Reverse recovery charge	Q _{rr} *5	$I_S = 7A$, $V_{GS} = 0V$ di/dt = 100A/ μ s		160	-	nC
Peak reverse recovery current	I _{rrm} *5			-	-	Α

● Typical transient thermal characteristics

Symbol	Value	Unit
R _{th1}	0.23371	
R _{th2}	0.65005	K/W
R _{th3}	0.3854	

Symbol	Value	Unit
C _{th1}	0.001451	
C _{th2}	0.01813	Ws/K
C_{th3}	0.32471	

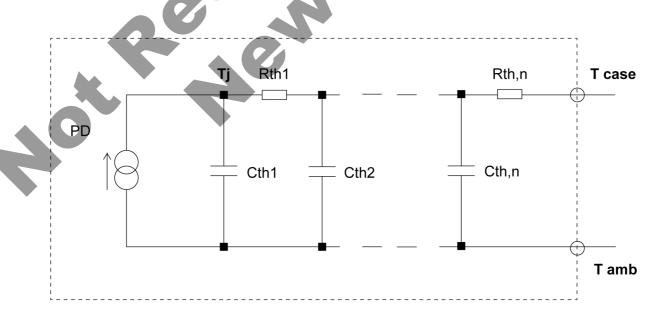


Fig.1 Power Dissipation Derating Curve

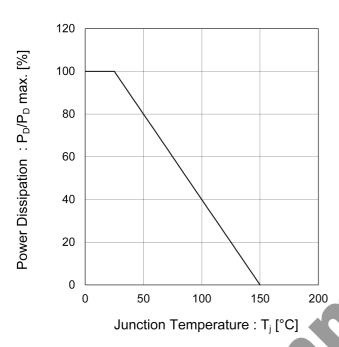


Fig.2 Maximum Safe Operating Area

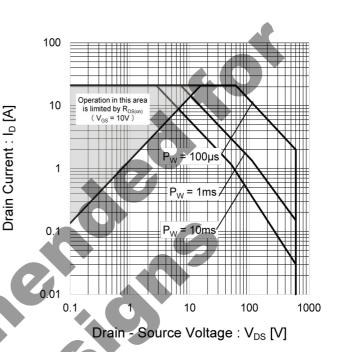


Fig.3 Drain Current Derating
Curve vs. Ambient Temperature

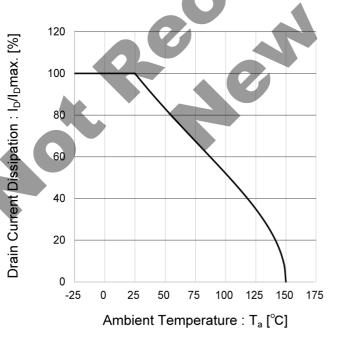


Fig.4 Avalanche Energy Derating
Curve vs. Junction Temperature

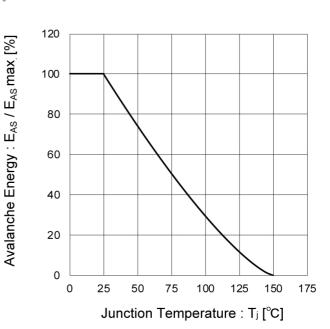


Fig.5 Typical Output Characteristics(I)

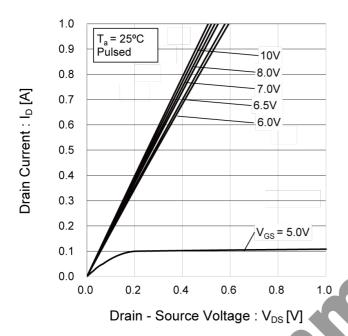
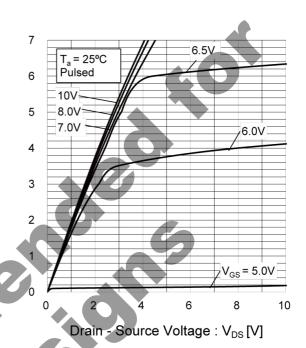


Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

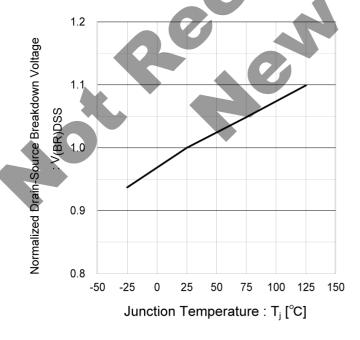


Fig.8 Typical Transfer Characteristics

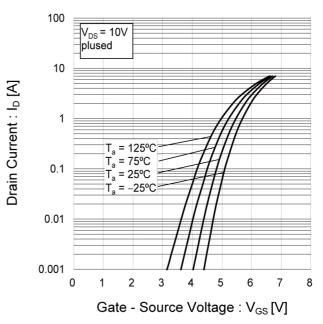


Fig.9 Normalized Gate Threshold Voltage. vs Junction Temperature

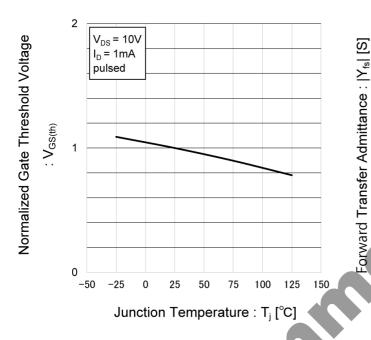


Fig.10 Forward Transfer Admittance vs.
Drain Current

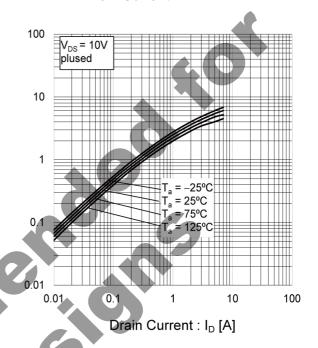


Fig.11 Static Drain - Source On - State
Resistance vs. Gate Source Voltage

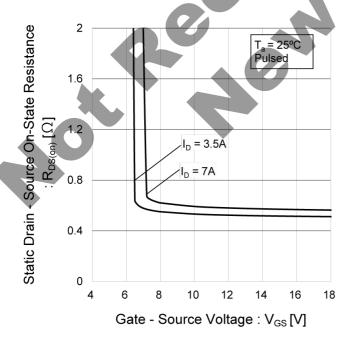


Fig.12 Normalized Static Drain - Source
On - State Resistance
vs. Junction Temperature

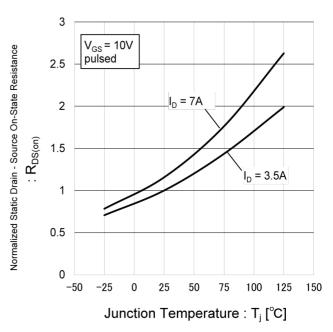


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current(I)

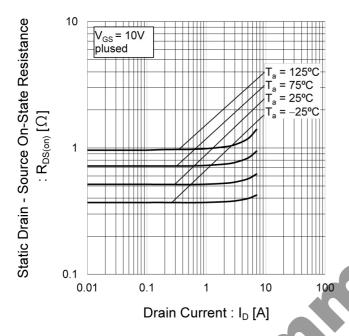


Fig.14 Typical Capacitance vs.
Drain - Source Voltage

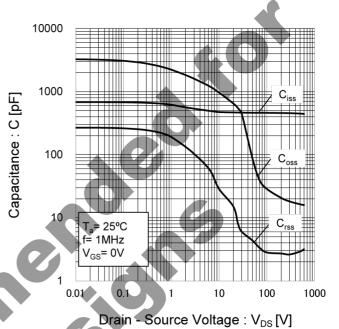


Fig.15 Switching Characteristics

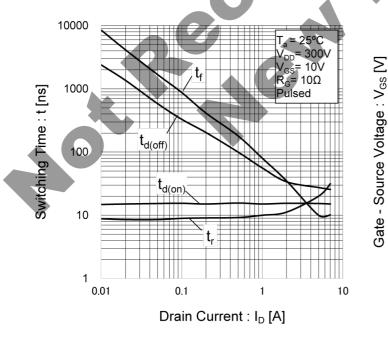


Fig.16 Dynamic Input Characteristics

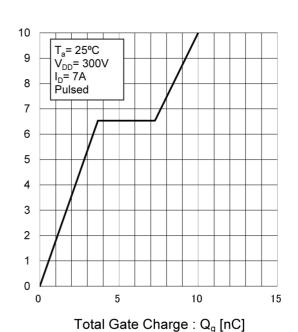


Fig.17 Inverse Diode Forward Current vs. Source - Drain Voltage

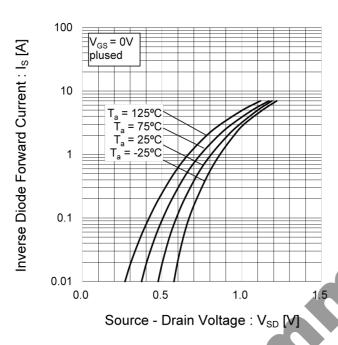
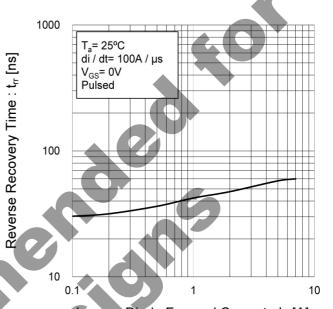


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current : I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

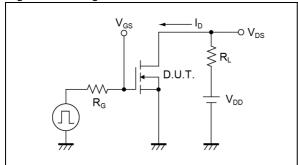


Fig.2-1 Gate Charge Measurement Circuit

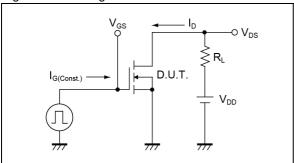


Fig.3-1 Avalanche Measurement Circuit

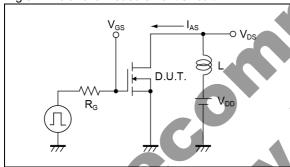


Fig.4-1 dv/dt Measurement Circuit

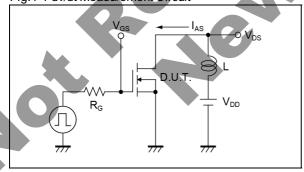


Fig.5-1 di/dt Measurement Circuit

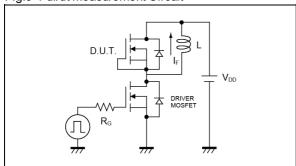


Fig.1-2 Switching Waveforms

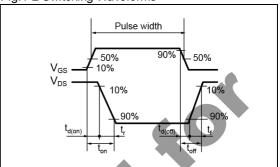


Fig.2-2 Gate Charge Waveform

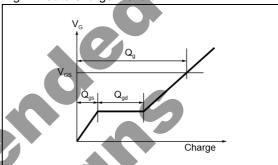


Fig.3-2 Avalanche Waveform

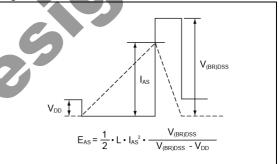


Fig.4-2 dv/dt Waveform

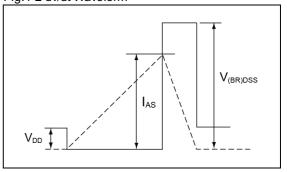
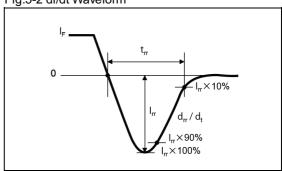
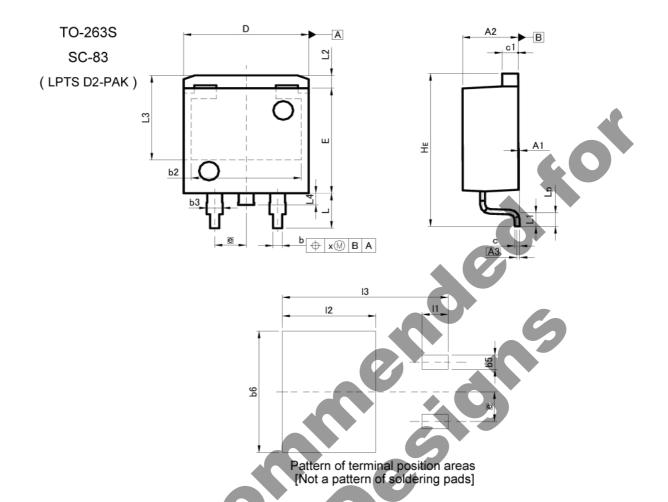


Fig.5-2 di/dt Waveform



Dimensions



MILIMETERS INCHES DIM MIN 0.000 0.169 MAX 0.012 0.185 MIN 0.00 MAX 0.30 4.30 4.70 0.010 0.25 0.027 0.68 0.98 0.039 0.350 0.045 0.057 1.44 0,30 0.012 0.60 0.024 1.10 9.80 0.043 0.386 cl 1.50 0.059 D 10.40 9.20 0.409 Έ 8,80 0.346 0.362 е 0.100 0.528 0.130 HE 12.80 13.40 0.504 3.30 0.106 П 1.20 0.047 L2 1.10 0.043 7.25 1.00 0.285 L3 L4 0.059 0.010 Lp 1.50 0.25 0.90 0.035

 DIM
 MILIMETERS
 INCHES

 MIN
 MAX
 MIN
 MAX

 b5
 1.23
 0.049

 b6
 10.40
 0.409

 I1
 2.10
 0.083

 I2
 7.55
 0.297

 I3
 13.40
 0.528

Dimension in mm/inches

Rev.003

Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CL ACCIII	CLASS II b	СГУССШ
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSII

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power, exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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When disposing Products please dispose them properly using an authorized industry waste company.

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Notice-PGA-E Rev.003

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